



40V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	Rds(on) max	I _{D MAX} $T_A = +25^{\circ}C$	
40V	34mΩ @ V _{GS} = 10V	6.5A	
	59mΩ @ V _{GS} = 4.5V	4.8A	

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

- Low Gate Threshold Voltage
- Low Input Capacitance
- · Fast Switching Speed
- Low Input/Output Leakage
- 100% Unclamped Inductive Switch (UIS) Test in Production
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMN4034SSSQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

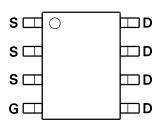
https://www.diodes.com/quality/product-definitions/

Mechanical Data

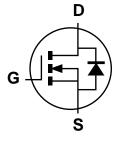
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed Over Copper Leadframe. Solderable per MIL-STD-202, Method 208@3
- Weight: 0.008 grams (Approximate)







Top View



Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN4034SSSQ-13	SO-8	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Load free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



Oll = Manufacturer's Marking
N4034SS = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 21 = 2021)
WW = Week (01 to 53)



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			VDSS	40	V
Gate-Source Voltage			Vgs	±20	V
Continuous Drain Correct (Note C) Vos. 40V	Steady	T _A = +25°C		6.5	^
Continuous Drain Current (Note 6) Vgs = 10V		$T_A = +70$ °C	ID	5.2	A
Maximum Continuous Body Diode Forward Current (Note 6)			Is	6.5	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			Ірм	36	Α
Avalanche Current L = 0.1mH			Eas	19	mJ
Avalanche Energy L = 0.1mH			IAS	18	А

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	T _A =+25°C	PD	1.4	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	RθJA	84.8	°C/W
Total Power Dissipation (Note 6)	T _A =+25°C	P _D	2.1	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	RθJA	58.9	°C/W
Thermal Resistance, Junction to Case (Note 5)	R _θ JC	33.9	°C/W	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

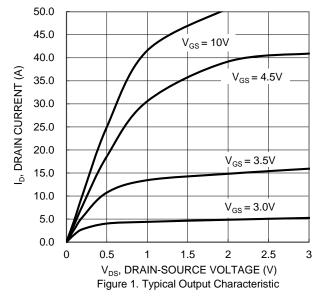
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	40	_	_	V	$I_D = 250 \mu A$, $V_{GS} = 0V$	
Zero Gate Voltage Drain Current	I _{DSS}		_	1	μA	V _{DS} = 40V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	Vgs(th)	1.0	_	3.0	V	$I_D = 250\mu A$, $V_{DS} = V_{GS}$	
Static Drain-Source On-Resistance	D		18.4	34	mΩ	V _G S = 10V, I _D = 6A	
Static Dialif-Source Off-Resistance	R _{DS(ON)}	_	24.5	59	11122	V _G S = 4.5V, I _D = 5A	
Diode Forward Voltage	VsD	_	0.87	1.1	V	Is = 6A, V _G S = 0V	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	920	_	pF	V _{DS} = 20V, V _{GS} = 0V -f = 1MHz	
Output Capacitance	Coss	_	76	_	pF		
Reverse Transfer Capacitance	Crss	_	59	_	pF		
Gate Resistance	R_g	_	2.1	_	Ω	VDS = 0V, $VGS = 0V$, $f = 1.0MHz$	
Total Gate Charge (VGS = 4.5V)	Qg	_	7.7	8	nC		
Total Gate Charge (VGS = 10V)	Qg	_	15.5	18	nC	V _{DS} = 20V	
Gate-Source Charge	Q_{gs}	_	2	_	nC	I _D = 6A	
Gate-Drain Charge	Q_{gd}	_	3	_	nC]	
Turn-On Delay Time	tD(ON)	_	4.8	_	ns		
Turn-On Rise Time	t _R	_	3	_	ns	$V_{DD} = 20V$, $V_{GS} = 10V$ $I_D = 1A$, $R_g \approx 6.0\Omega$	
Turn-Off Delay Time	t _{D(OFF)}	_	23	_	ns		
Turn-Off Fall Time	tF	_	7	_	ns		
Reverse Recovery Time	t _{RR}		11.9	_	ns	I _S = 2.5A, di/dt = 100A/µs	
Reverse Recovery Charge	Qrr	_	4.9	_	nC		

Notes:

- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.





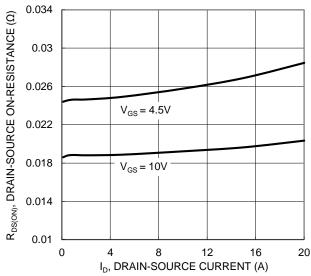


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

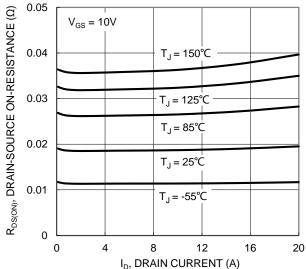


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

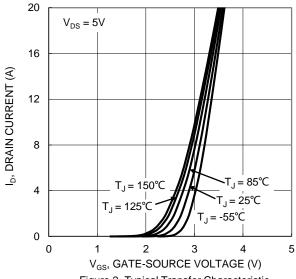
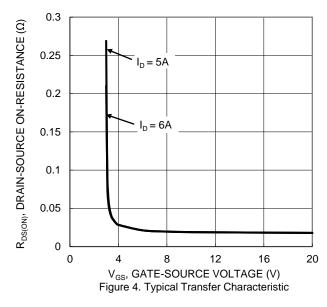


Figure 2. Typical Transfer Characteristic



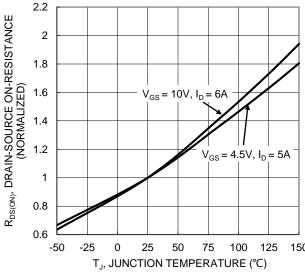


Figure 6. On-Resistance Variation with Junction Temperature



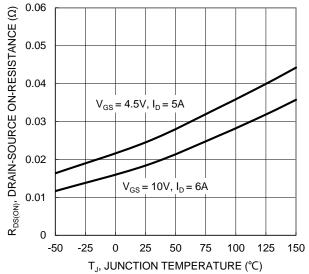
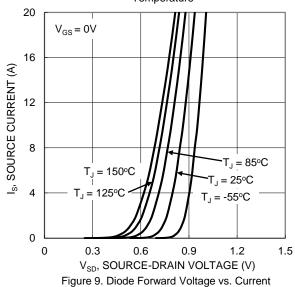
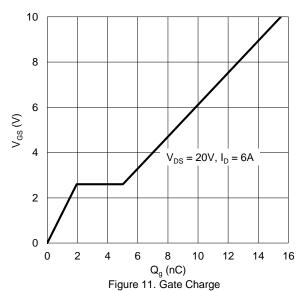


Figure 7. On-Resistance Variation with Junction Temperature





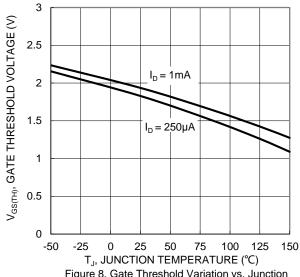
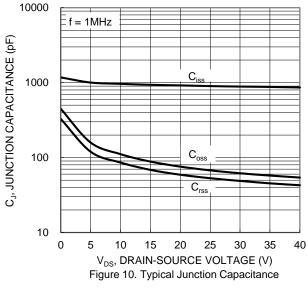
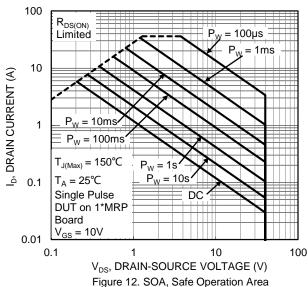


Figure 8. Gate Threshold Variation vs. Junction Temperature







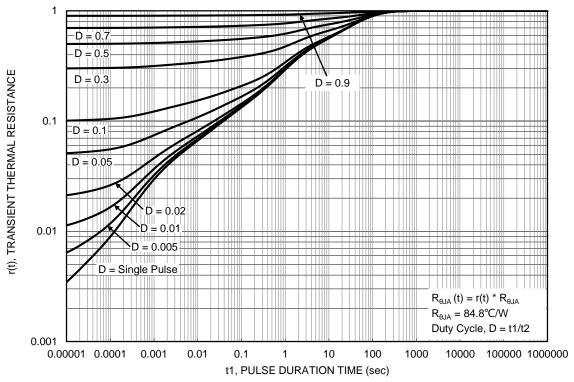


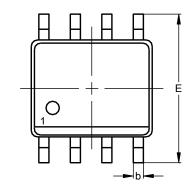
Figure 13. Transient Thermal Resistance

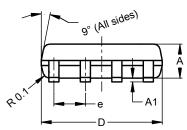


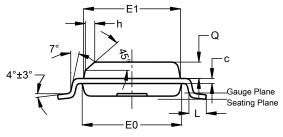
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8





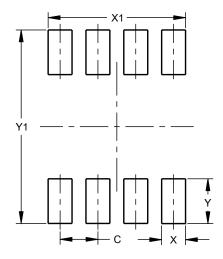


SO-8						
Dim	Min	Max	Тур			
Α	1.40	1.50	1.45			
A1	0.10	0.20	0.15			
þ	0.30	0.50	0.40			
C	0.15	0.25	0.20			
D	4.85	4.95	4.90			
Е	5.90	6.10	6.00			
E1	3.80	3.90	3.85			
E0	3.85	3.95	3.90			
e 1.27						
h	-		0.35			
٦	0.62	0.82	0.72			
Ø	0.60	0.70	0.65			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



Dimensions	Value (in mm)			
С	1.27			
Х	0.802			
X1	4.612			
Υ	1.505			
Y1	6.50			



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